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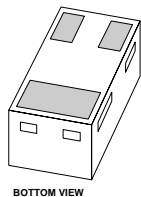
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Kind regards,

Team Nexperia



BOTTOM VIEW

PMZ390UN

N-channel TrenchMOS standard level FET

Rev. 01 — 12 July 2007

Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology.

1.2 Features

- Profile 55 % lower than SOT23
- Low on-state resistance
- Leadless package
- Footprint 90 % smaller than SOT23
- Fast switching
- Standard level compatible threshold

1.3 Applications

- Driver circuits
- Load switching in portable appliances

1.4 Quick reference data

- $V_{DS} \leq 30 \text{ V}$
- $I_D \leq 1.78 \text{ A}$
- $R_{DS(on)} \leq 460 \text{ m}\Omega$
- $P_{tot} \leq 2.50 \text{ W}$

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	gate (G)	<p>Transparent top view</p> <p>SOT883 (SC-101)</p>	<p>mbb076</p>
2	source (S)		
3	drain (D)		

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
PMZ390UN	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883

4. Limiting values

CAUTION



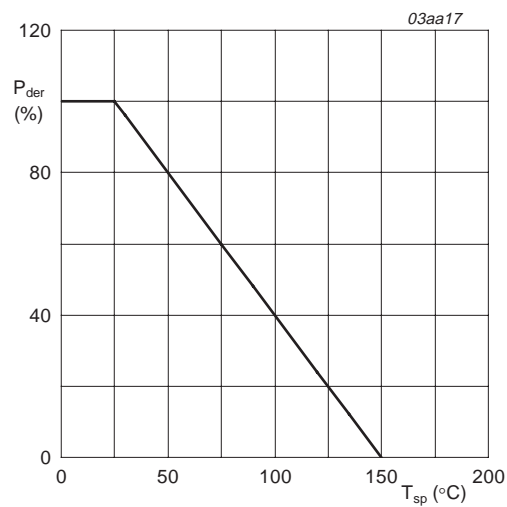
This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

Table 3. Limiting values

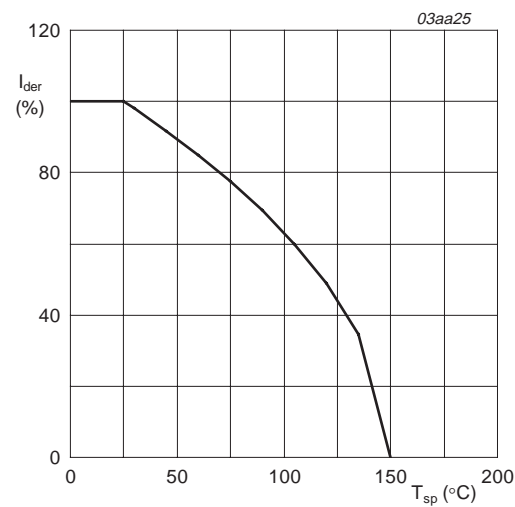
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 150\text{ °C}$	-	30	V
V_{DGR}	drain-gate voltage (DC)	$25\text{ °C} \leq T_j \leq 150\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$	-	30	V
V_{GS}	gate-source voltage		-	±8	V
I_D	drain current	$T_{mb} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$; see Figure 2 and 3	-	1.78	A
		$T_{mb} = 100\text{ °C}$; $V_{GS} = 10\text{ V}$; see Figure 2	-	1.13	A
I_{DM}	peak drain current	$T_{mb} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; see Figure 3	-	3.56	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 1	-	2.50	W
T_{stg}	storage temperature		-55	+150	°C
T_j	junction temperature		-55	+150	°C
Source-drain diode					
I_S	source current	$T_{mb} = 25\text{ °C}$	-	1.78	A
I_{SM}	peak source current	$T_{mb} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	-	3.56	A
Electrostatic discharge					
V_{esd}	electrostatic discharge voltage	all pins			
		human body model; $C = 100\text{ pF}$; $R = 1.5\text{ k}\Omega$	-	60	V
		machine model; $C = 200\text{ pF}$	-	30	V



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

Fig 1. Normalized total power dissipation as a function of solder point temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100 \%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature

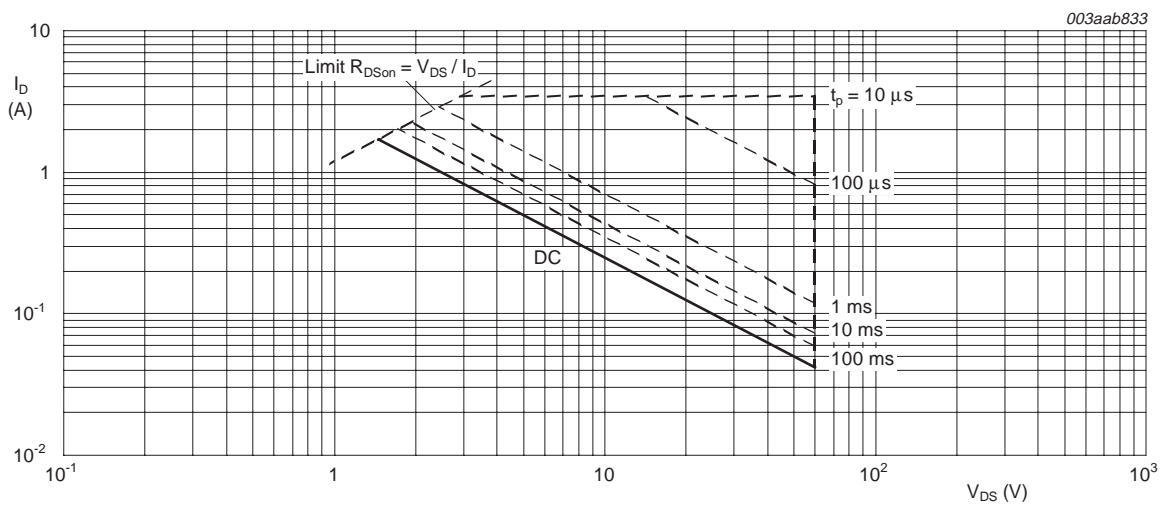


Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	see Figure 4	-	-	50	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1] -	670	-	K/W

[1] Mounted on a printed-circuit board; vertical in still air.

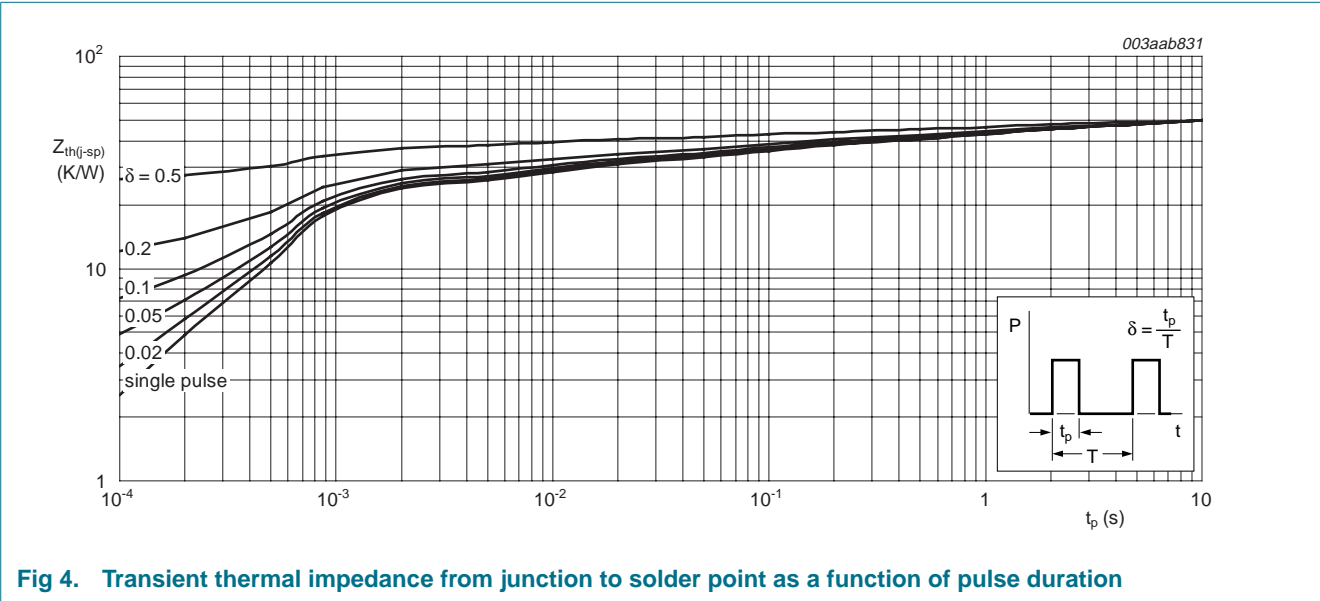


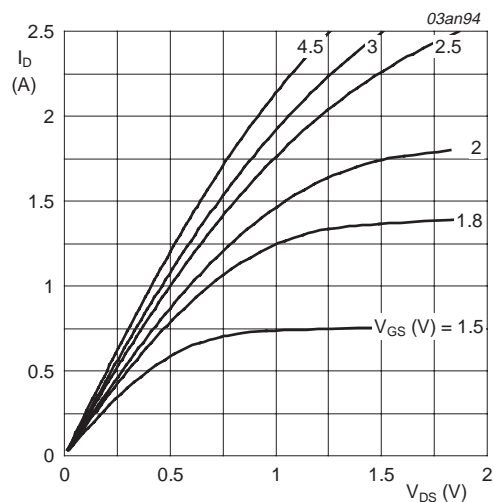
Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration

6. Characteristics

Table 5. Characteristics

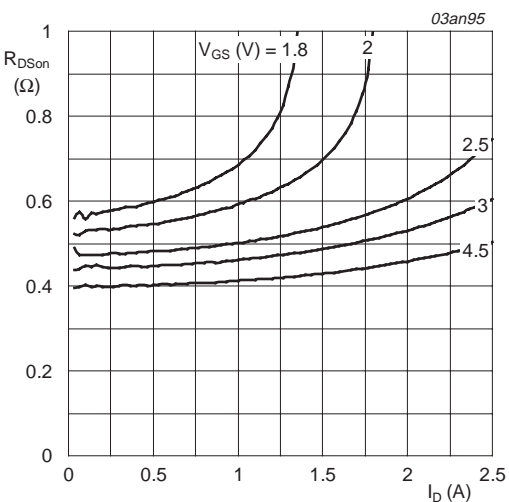
$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 10\text{ }\mu\text{A}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^{\circ}\text{C}$	30	-	-	V
		$T_j = -55\text{ }^{\circ}\text{C}$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 0.25\text{ mA}$; $V_{DS} = V_{GS}$; see Figure 9 and 10 $T_j = 25\text{ }^{\circ}\text{C}$	0.45	0.7	0.95	V
		$T_j = 150\text{ }^{\circ}\text{C}$	0.25	-	-	V
		$T_j = -55\text{ }^{\circ}\text{C}$	-	-	1.15	V
I_{DSS}	drain leakage current	$V_{DS} = 30\text{ V}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^{\circ}\text{C}$	-	-	1	μA
		$T_j = 150\text{ }^{\circ}\text{C}$	-	-	100	μA
I_{GSS}	gate leakage current	$V_{GS} = \pm 8\text{ V}$; $V_{DS} = 0\text{ V}$	-	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}$; $I_D = 0.2\text{ A}$; see Figure 6 and 8 $T_j = 25\text{ }^{\circ}\text{C}$	-	390	460	m Ω
		$T_j = 150\text{ }^{\circ}\text{C}$	-	663	782	m Ω
		$V_{GS} = 2.5\text{ V}$; $I_D = 0.1\text{ A}$; see Figure 6 and 8	-	460	560	m Ω
		$V_{GS} = 1.8\text{ V}$; $I_D = 0.075\text{ A}$; see Figure 6 and 8	-	550	730	m Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 1\text{ A}$; $V_{DS} = 15\text{ V}$; $V_{GS} = 4.5\text{ V}$; see Figure 11 and 12	-	0.89	-	nC
Q_{GS}	gate-source charge		-	0.1	-	nC
Q_{GD}	gate-drain charge		-	0.2	-	nC
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 25\text{ V}$; $f = 1\text{ MHz}$; see Figure 14	-	43	-	pF
C_{oss}	output capacitance		-	7.7	-	pF
C_{rss}	reverse transfer capacitance		-	4.8	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15\text{ V}$; $R_L = 15\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $R_G = 6\text{ }\Omega$	-	4	-	ns
t_r	rise time		-	7.5	-	ns
$t_{d(off)}$	turn-off delay time		-	18	-	ns
t_f	fall time		-	4.5	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 0.3\text{ A}$; $V_{GS} = 0\text{ V}$; see Figure 13	-	0.76	1.2	V



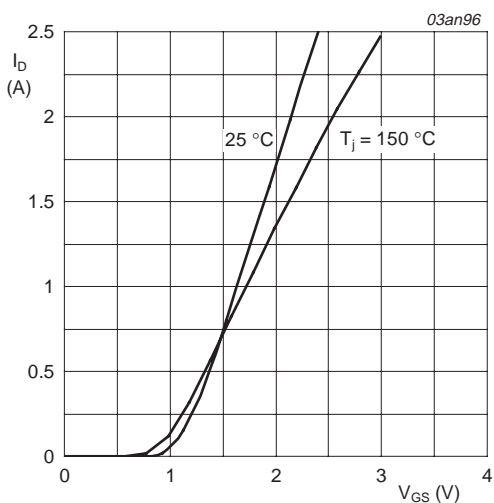
T_j = 25 °C

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



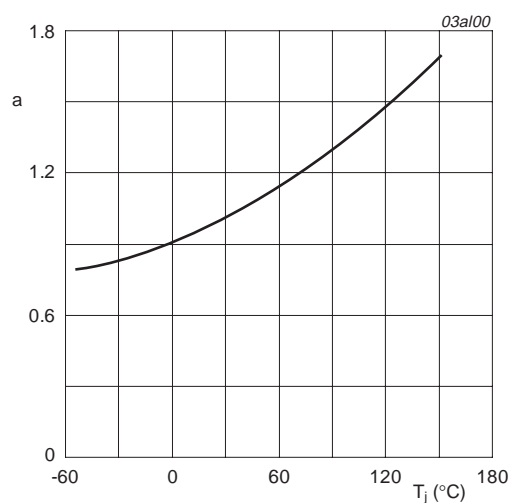
T_j = 25 °C

Fig 6. Drain-source on-state resistance as a function of drain current; typical values



T_j = 25 °C and 150 °C; V_{DS} > I_D × R_{DSon}

Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}C)}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature

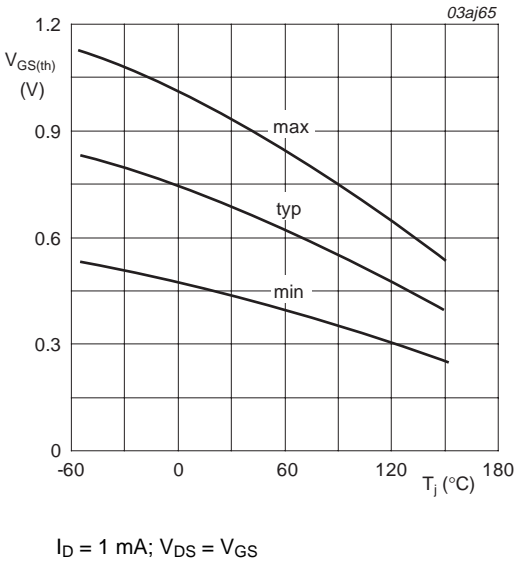


Fig 9. Gate-source threshold voltage as a function of junction temperature

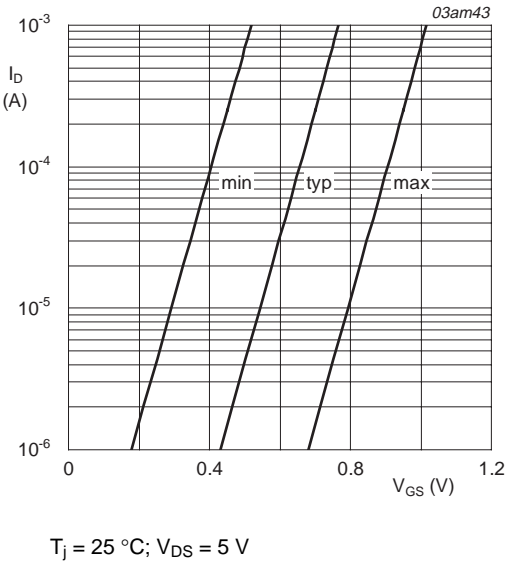


Fig 10. Sub-threshold drain current as a function of gate-source voltage

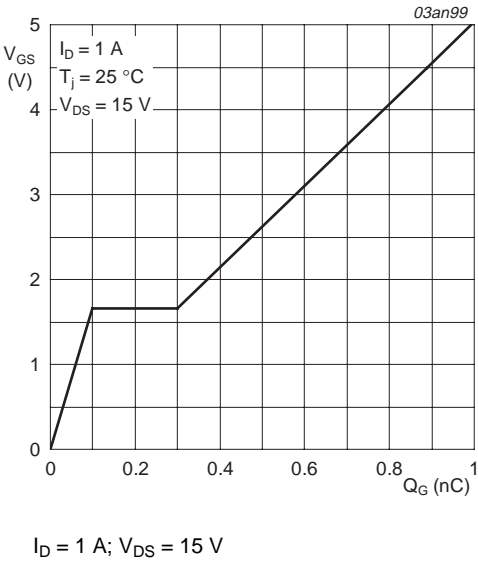


Fig 11. Gate-source voltage as a function of gate charge; typical values

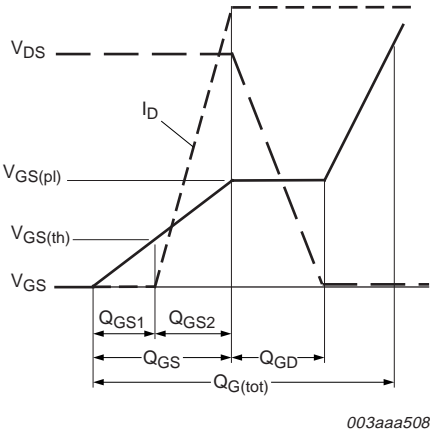
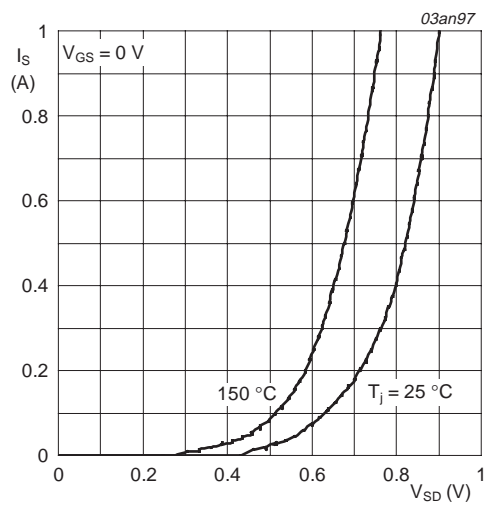
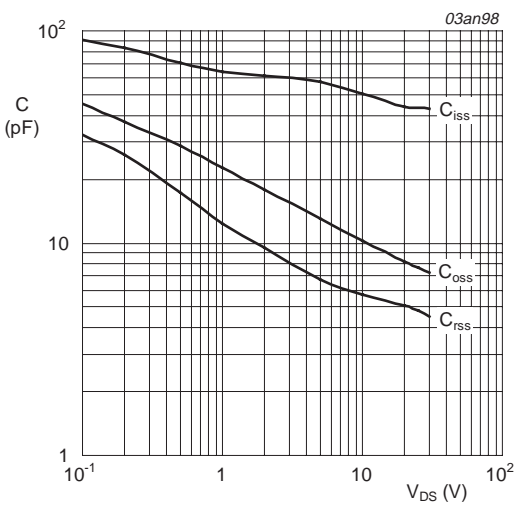


Fig 12. Gate charge waveform definitions



$T_j = 25\text{ °C}$ and 150 °C ; $V_{GS} = 0\text{ V}$

Fig 13. Source current as a function of source-drain voltage; typical values



$V_{GS} = 0\text{ V}$; $f = 1\text{ MHz}$

Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

7. Package outline

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883

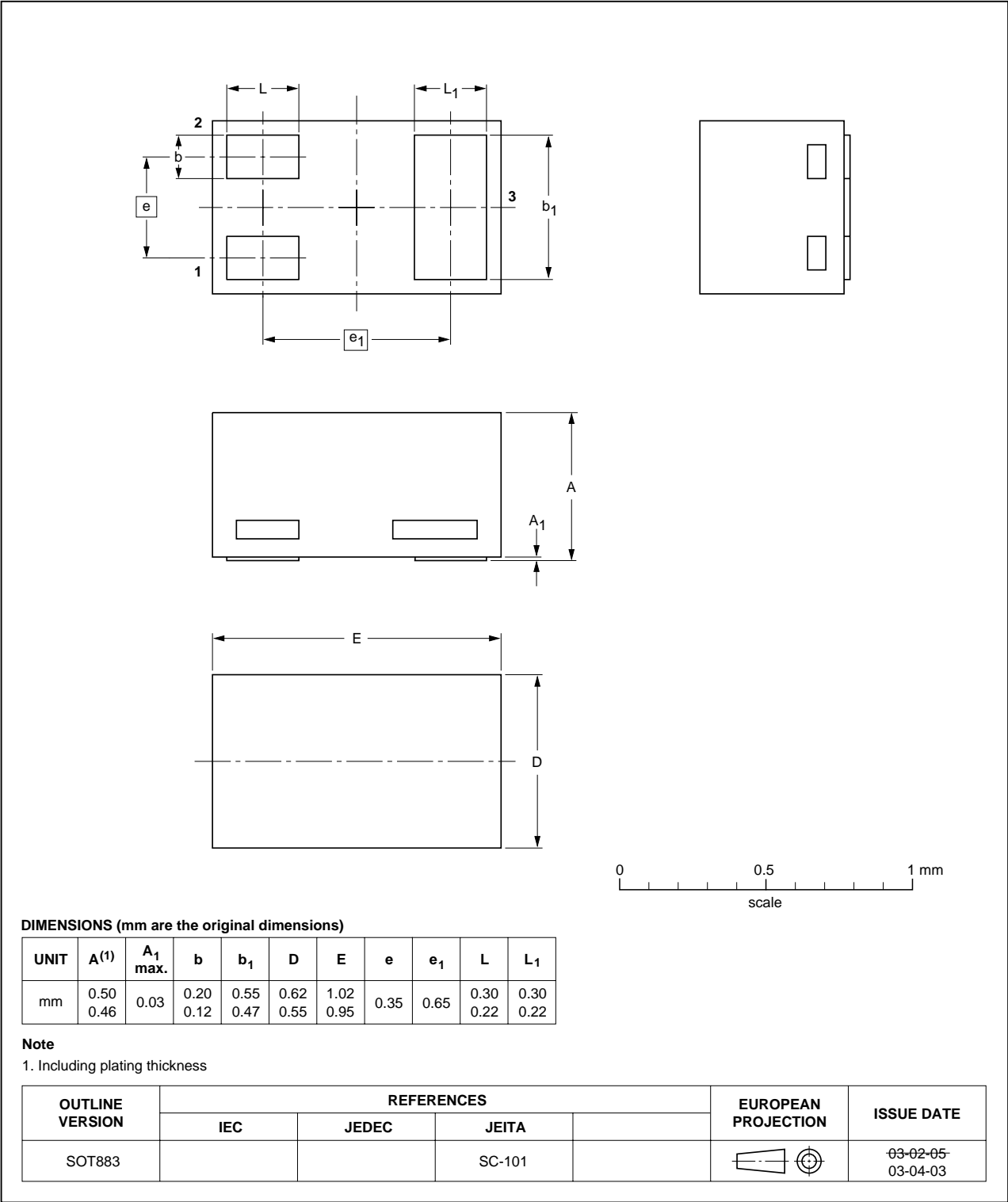
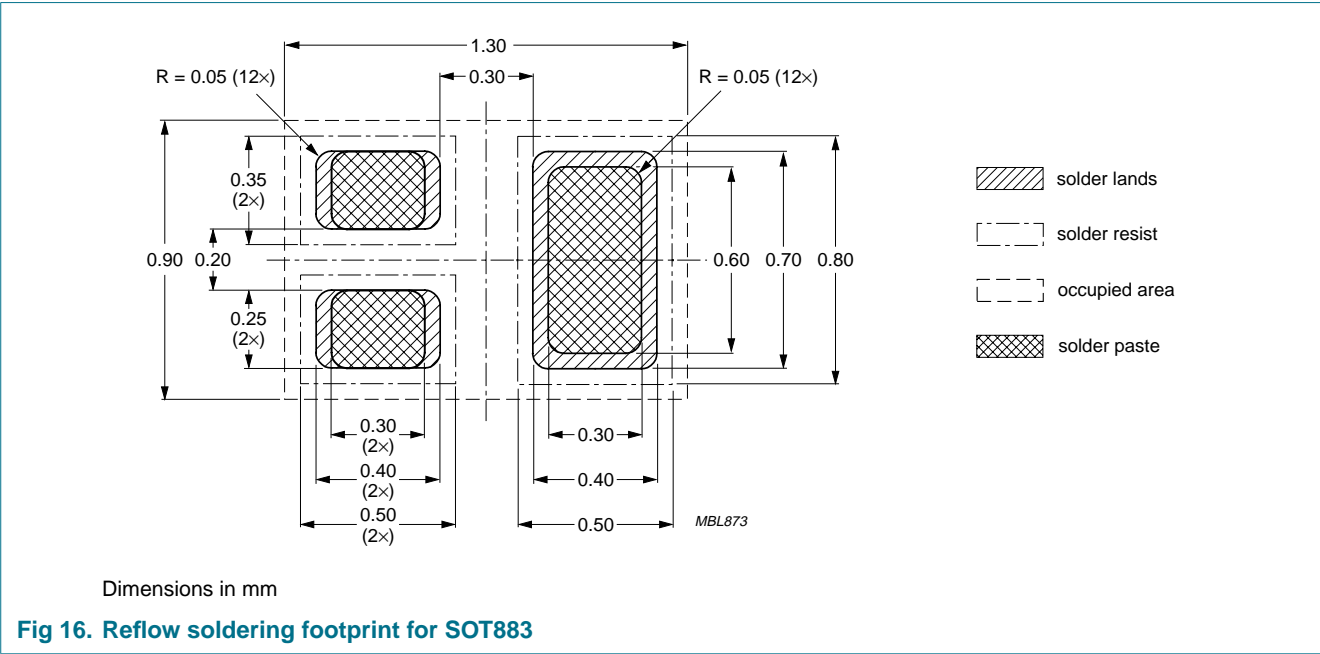


Fig 15. Package outline SO883 (SC-101)

8. Soldering



9. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMZ390UN _1	20070712	Product data sheet	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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